

Amendments to the Specification:

Please replace the Title of the application (beginning at page 1, line 3) with the following amended Title:

METHOD FOR RAPIDLY [[FAST]] HEATING AND COOLING APPARATUS FOR SEMICONDUCTOR WAFERS

Please replace the paragraph beginning at page 1, line 5 with the following amended paragraph:

The present application is a divisional of U.S. Application Serial No. 09/197,284 filed on November 20, 1998, now abandoned.

Please replace the paragraph beginning at page 15, line 19 with the following amended paragraph:

Referring to Figure 4, an alternative embodiment of a heating cooling device 60 that may be used in the apparatus and process of the present invention is illustrated. Similar to the embodiment illustrated in Figures 2 and 3, in this embodiment, heating cooling device 60 includes a cooling member 64 that defines one or more cooling channels 66 for circulating a cooling fluid, such as a liquid. In this embodiment, however, cooling member 64 further defines at least one gas passage 68.